

# **JMM4719ND**

**Product Preview** 

**30V N-Channel MOSFET** 



#### **Features**

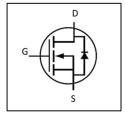
- Advanced shielded-gate technology
- Ultra-low on-resistance and gate-charge
- RoHS compliant
- 100% avalanche tested

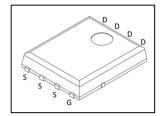


<b>Product Summary</b>				
V <sub>DS</sub>	30V			
D	0.85 mΩ (Typ.)			
R <sub>DS(ON)</sub>	1.05 mΩ (Max.)			

# **Applications**

- Motor controllers
- DC-to-DC convertors
- Battery-driven electronic products, electrical equipment and machines





#### **Ordering Information**

Part Number	Marking	Package	Packaging
JMM4719ND	MM4719ND	DFN5x6	Tape & Reel



#### **Absolute Maximum Ratings**

Parameter	Symbol	Limit	Unit
Drain-to-Source Voltage	V <sub>DS</sub>	30	V
Gate-to-Source Voltage	V <sub>GS</sub>	±20	] V
Continuous Drain Current, Silicon limited (T <sub>c</sub> = 25°C) <sup>(1)</sup>	ID	260	
Continuous Drain Current, Silicon limited (T <sub>c</sub> = 100°C) <sup>(1)</sup>	ID	164	
Continuous Drain Current, Silicon limited (T <sub>A</sub> = 25°C) (2), (5)	ID	41	Α
Continuous Drain Current, Silicon limited (T <sub>A</sub> = 100°C) (2), (5)	I <sub>D</sub>	26	
Pulsed Drain Current (3)	I <sub>DM</sub>	400	
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	114	W
Linear Derating Factor	-	0.91	W/°C
Single Pulse Avalanche Energy (4)	Eas	181	mJ
Avalanche Current (4)	l <sub>AS</sub>	42	Α
Junction Temperature	Tı	-55 to 150	°C
Storage Temperature	T <sub>STG</sub>	-55 to 150	

#### **Thermal Characteristics**

Parameter	Symbol	Max	Unit
Junction-to-Ambient Thermal Resistance (5)	R <sub>θJA</sub>	45	°C /\\
Junction-to-Case Thermal Resistance	Rөлс	1.1	°C/W

# Static Electrical Characteristics (6)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30	-	-	.,
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	1.1	-	2.2	V
Drain-to-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	-	-	1	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Dunin to Course On Bookstone		V <sub>GS</sub> = 10V, I <sub>D</sub> = 50A	-	0.85	1.05	mΩ
Drain-to-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 50A	-	1.2	1.55	mΩ



# **Dynamic Electrical Characteristics** (6)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> = 5V, I <sub>D</sub> = 30A	-	126	-	S
Total Gate Charge	Qg	V <sub>GS</sub> = 10V,	-	107	-	
Gate-to-Source Charge	Qgs	V <sub>DS</sub> = 15V,	-	17	-	nC
Gate-to-Drain Charge	Q <sub>gd</sub>	I <sub>D</sub> = 30A	-	18	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = 10V,	-	22	-	
Rise Time	tr	V <sub>DS</sub> = 15V,	-	20	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	I <sub>D</sub> = 30A,	-	83	-	ns
Fall Time	t <sub>f</sub>	$R_G = 3.0\Omega$	-	25	-	
Input Capacitance	Ciss	V <sub>GS</sub> = 0V,	-	7400	-	
Output Capacitance	Coss	f = 1MHz,	-	2555	-	pF
Reverse Transfer Capacitance	Crss	V <sub>DS</sub> = 15V	-	110	-	

# Diode Characteristics (6)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 50A	-	0.8	-	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 30A,	-	55	-	ns
Reverse Recovery Charge	Qrr	dls/dt = 100A/μs	-	100	-	nC

- (1) Rated according to  $R_{\theta JC}$ .
- (2) Rated according to  $R_{\theta JA}$ .
- (3) Limited by maximum  $T_{\scriptscriptstyle J}$ .
- (4)  $T_A = 25$ °C, L = 0.1mH,  $I_{AS} = 42$ A.
- (5) Surface–mounted on 1 inch² FR4 board, 2 oz Cu.
- (6)  $T_J = 25$ °C unless otherwise specified.



#### **Typical Electrical Characteristics**

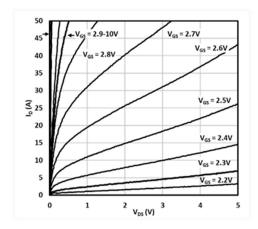


Fig. 1 Output characteristics

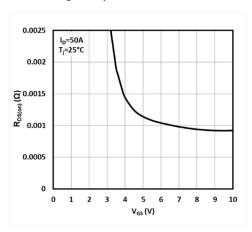


Fig.3 On-resistance vs. gate voltage

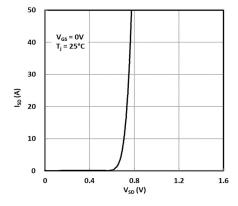


Fig.5 Source-to-drain diode forward characteristics

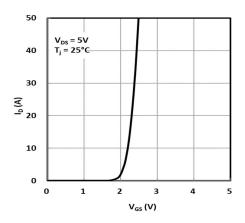


Fig. 2 Transfer characteristics

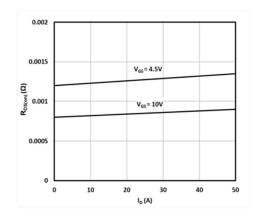


Fig.4 On-resistance vs. drain current

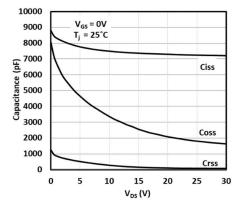


Fig.6 Capacitance vs. drain-to-source voltage



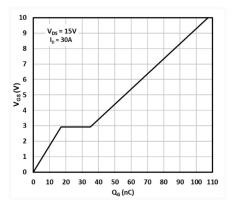


Fig.7 Gate-to-source voltage vs. gate charge

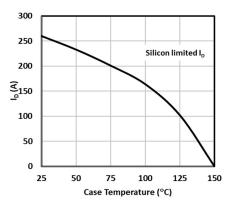


Fig.8 Maximum drain current vs. case temperature

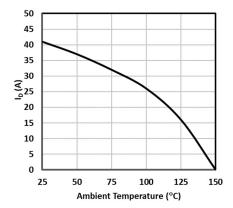
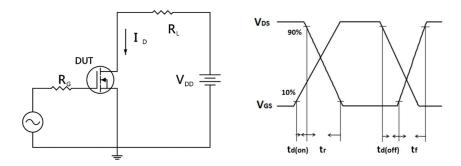


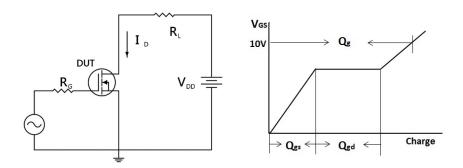
Fig.9 Maximum drain current vs. ambient temperature



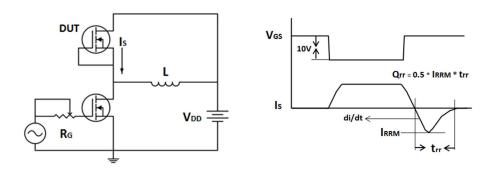
#### **Test Circuits and Waveforms**



Resistive switching time test circuit & waveforms

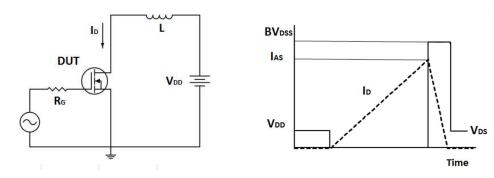


Gate charge test circuit & waveform



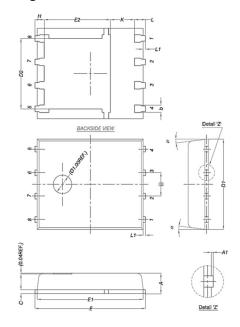
Peak diode recovery dv/dt test circuit & waveforms





Unclamped inductive switching test circuit & waveforms

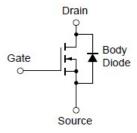
#### **Package Drawing**



	N	IILLIMETI	ERS
DIM.	MIN.	NOM.	MAX.
Α	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
С	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
Ε	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
е		1.27 BSC	
Н	0.41	0.51	0.61
K	1.10	-	670
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	O°	12	12°

DFN 5x6

# **Equivalent Circuit**





#### Revision history of JMM4719ND specification

Version	Change Items	Effective Date
1.00	Initial Release	18-May-21



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